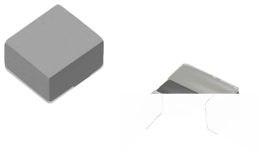
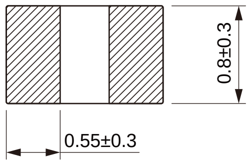
MDTE Series
Wire Wound Molded SMD Power Inductors
Size 160808



Dimensions: [mm]

Land Pattern: [mm]

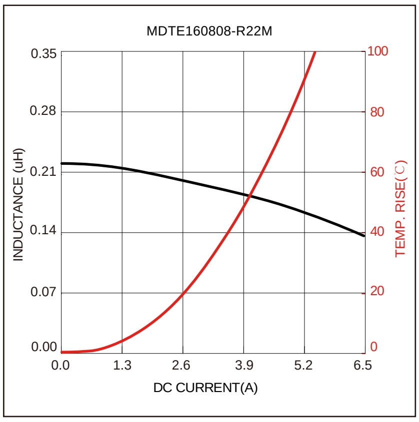


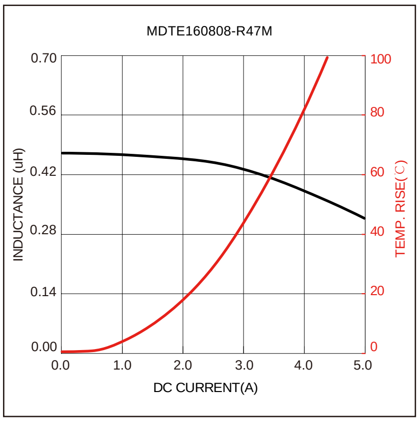
Electrical Properties:

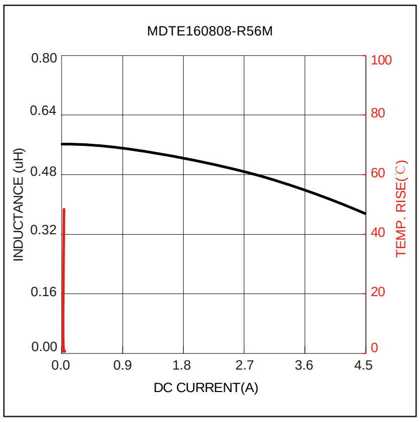
	(µH)		Saturation (A)	Saturation (A)	(A)	(A)	(mΩ)
MDTE160808-R22M	0.22	±20%	5.5	5.0	3.4	3.0	40
MDTE160808-R47M	0.47	±20%	4.7	4.2	2.8	2.5	100
MDTE160808-R56M	0.56	±20%	4.1	3.6	2.4	2.2	110
MDTE160808-R68M	0.68	±20%	3.3	3.0	2.2	2.0	138
MDTE160808-1R0M	1.00	±20%	3.0	2.6	2.1	1.8	200

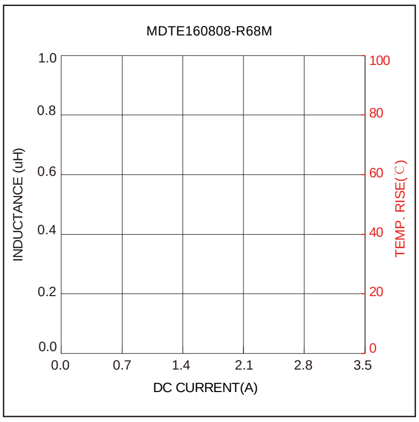
Saturation Current will cause L to drop approximately 30%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

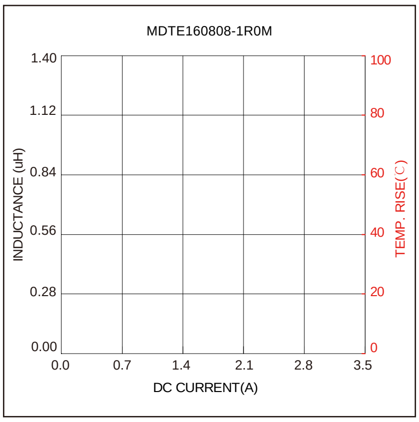
Typical Electrical Characteristics:



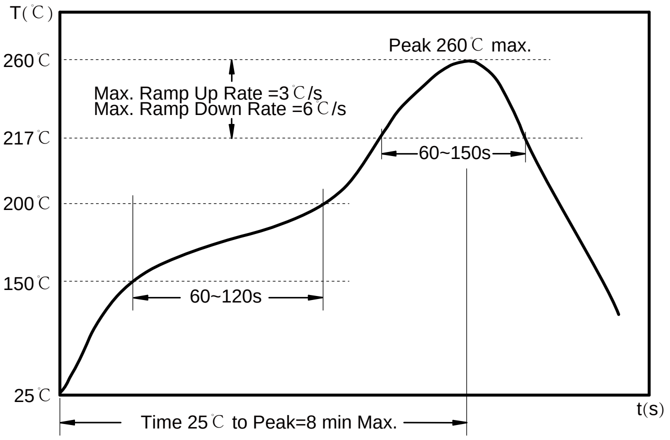








Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

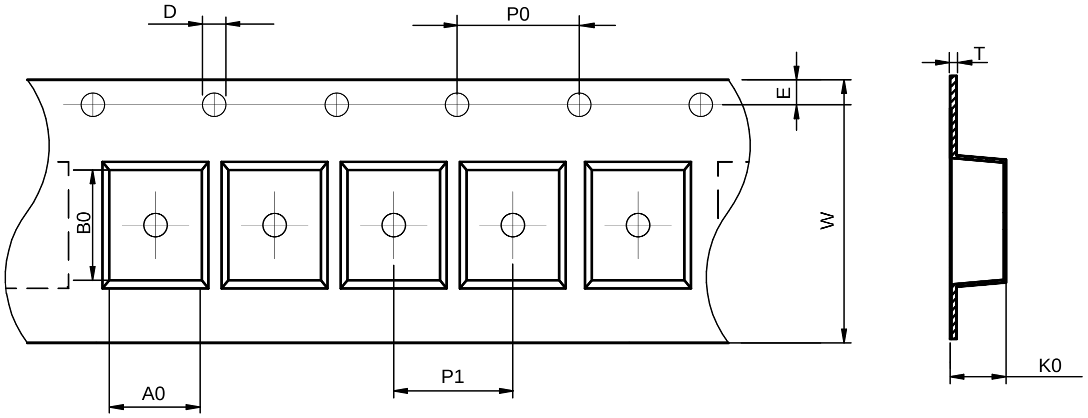
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 2x max.

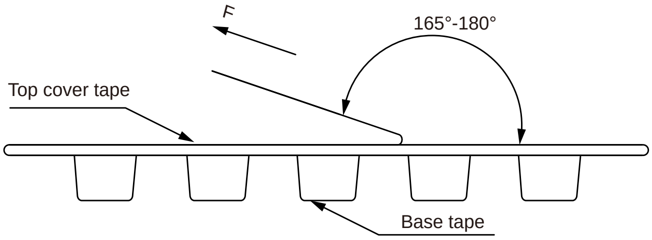
Packaging Information:

Tape Dimension:



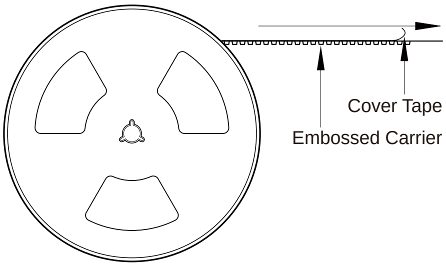
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE160808	1.1±0.1	1.9±0.1	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.1	1.0±0.1	1.75±0.1	0.25±0.05

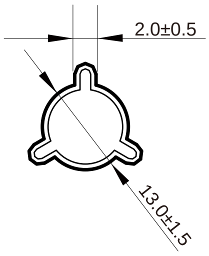
Peel force of top cover tape:

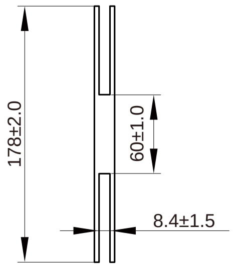


The peel force of top cover tape shall be between 0.1 to 0.98 N

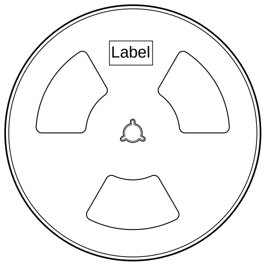
Reel Dimension: [mm]



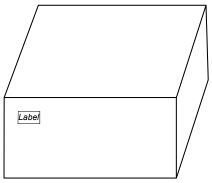




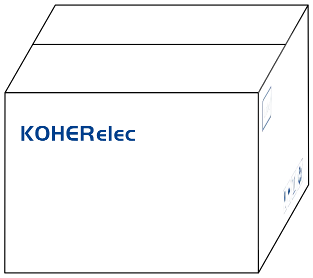
Packaging Quantity:



3000 Pcs/Reel



5 Reel /Inner box(15K Pcs)



8 Inner box/Carton box(120K Pcs)

Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.